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Applicant: Thomas J. Massingill, et al.
Confirmation No.: 6199
Serial No.: 09/997,589
Filed: November 29, 2001
For: *Multi-Chip Module and Method for
Forming and Method for Deplating
Defective Capacitors*
Art Group Unit: 1756
Examiner: Thai, Luan C.
Atty. Dkt.: 6136-53804 (25916-162)

**CERTIFICATE OF
MAILING/TRANSMISSION
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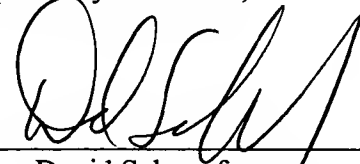
**LETTER TRANSMITTING FORMAL DRAWINGS
TO THE OFFICIAL DRAFTSPERSON**

Sir:

Transmitted herewith are formal drawings for the above-identified application bearing
Figures 1 – 87 on thirty-four (34) drawing sheets.

July 23, 2004
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Respectfully submitted,

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